

DESCRIPTION

The SI2305 is the high cell density trenched P-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The SI2305 meet the RoHS and Green Product requirement with full function reliability approved.

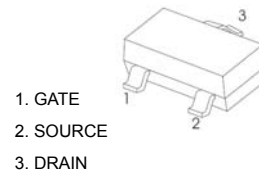
FEATURES

Super Low Gate Charge
Green Device Available
Excellent CdV/dt effect decline
Advanced high cell density Trench technology

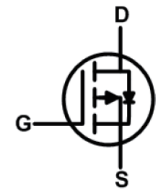
V_{DS} -20 V
 I_D -4.1 A
 $R_{DS(ON)}$ 33 m Ω

A5SHB

SOT-23



Equivalent Circuit



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings

| Symbol | Parameter | Rating | Units |
|--------------------------------|---|------------|------------------|
| V_{DS} | Drain-Source Voltage | -20 | V |
| V_{GS} | Gate-Source Voltage | ± 12 | V |
| $I_D @ T_A = 25^\circ\text{C}$ | Continuous Drain Current, $V_{GS} @ -4.5\text{V}^1$ | -4.1 | A |
| $I_D @ T_A = 70^\circ\text{C}$ | Continuous Drain Current, $V_{GS} @ -4.5\text{V}^1$ | -3.0 | A |
| I_{DM} | Pulsed Drain Current ² | -16 | A |
| $P_D @ T_A = 25^\circ\text{C}$ | Total Power Dissipation ³ | 1.31 | W |
| $P_D @ T_A = 70^\circ\text{C}$ | Total Power Dissipation ³ | 0.84 | W |
| T_{STG} | Storage Temperature Range | -55 to 150 | $^\circ\text{C}$ |
| T_J | Operating Junction Temperature Range | -55 to 150 | $^\circ\text{C}$ |

Thermal Data

| Symbol | Parameter | Typ. | Max. | Unit |
|-----------------|--|------|------|--------------------|
| $R_{\theta JA}$ | Thermal Resistance Junction-Ambient ¹ | --- | 125 | $^\circ\text{C/W}$ |
| $R_{\theta JA}$ | Thermal Resistance Junction-Ambient ¹ ($t \leq 10\text{s}$) | --- | --- | $^\circ\text{C/W}$ |

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

| Symbol | Parameter | Test Condition | Min. | Typ. | Max. | Units |
|---|---|---|------|------|-----------|------------|
| Off Characteristic | | | | | | |
| $V_{(BR)DSS}$ | Drain-Source Breakdown Voltage | $V_{GS}=0V, I_D=-250\mu A$ | -20 | - | - | V |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS}=-20V, V_{GS}=0V,$ | - | - | -1 | μA |
| I_{GSS} | Gate to Body Leakage Current | $V_{DS}=0V, V_{GS}=\pm 12V$ | - | - | ± 100 | nA |
| On Characteristics | | | | | | |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS}=V_{GS}, I_D=-250\mu A$ | -0.4 | -0.7 | -1.0 | V |
| $R_{DS(on)}$ | Static Drain-Source on-Resistance <small>note2</small> | $V_{GS}=-4.5V, I_D=-4.1A$ | - | 33 | 45 | m Ω |
| | | $V_{GS}=-2.5V, I_D=-3A$ | - | 42 | 60 | |
| Dynamic Characteristics | | | | | | |
| C_{iss} | Input Capacitance | $V_{DS}=-10V, V_{GS}=0V,$ $f=1.0MHz$ | - | 830 | - | pF |
| C_{oss} | Output Capacitance | | - | 132 | - | pF |
| C_{rss} | Reverse Transfer Capacitance | | - | 85 | - | pF |
| Q_g | Total Gate Charge | $V_{DS}=-10V, I_D=-2A,$ $V_{GS}=-4.5V$ | - | 8.8 | - | nC |
| Q_{gs} | Gate-Source Charge | | - | 1.4 | - | nC |
| Q_{gd} | Gate-Drain("Miller") Charge | | - | 1.9 | - | nC |
| Switching Characteristics | | | | | | |
| $t_{d(on)}$ | Turn-on Delay Time | $V_{DD}=-10V, I_D=-3.3A,$ $R_G=1\Omega, V_{GEN}=-4.5V$ | - | 10 | - | ns |
| t_r | Turn-on Rise Time | | - | 32 | - | ns |
| $t_{d(off)}$ | Turn-off Delay Time | | - | 50 | - | ns |
| t_f | Turn-off Fall Time | | - | 51 | - | ns |
| Drain-Source Diode Characteristics and Maximum Ratings | | | | | | |
| I_S | Maximum Continuous Drain to Source Diode Forward Current | | - | - | -5.0 | A |
| I_{SM} | Maximum Pulsed Drain to Source Diode Forward Current | | - | - | -16 | A |
| V_{SD} | Drain to Source Diode Forward Voltage | $V_{GS}=0V, I_S=-4.1A$ | - | - | -1.2 | V |

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$

RATING AND CHARACTERISTIC CURVES

Figure 1: Output Characteristics

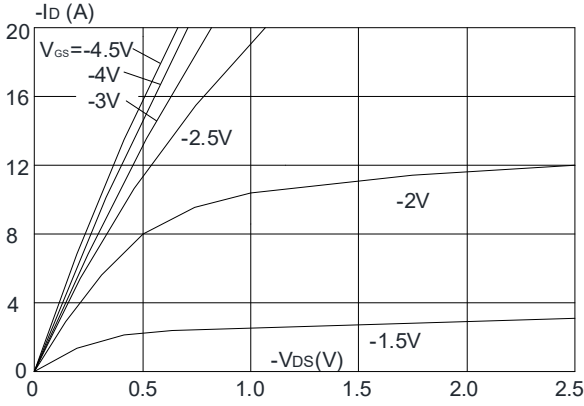


Figure 2: Typical Transfer Characteristics

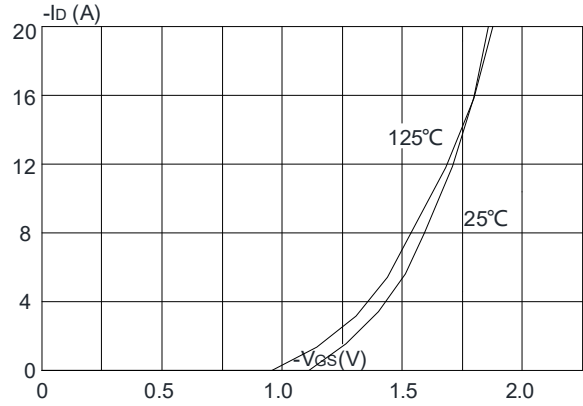


Figure 3: On-resistance vs. Drain Current

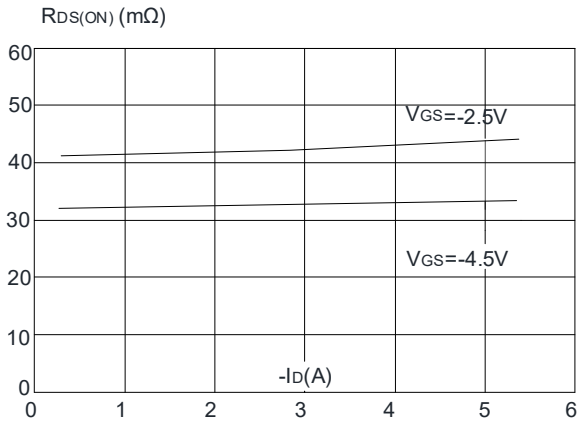


Figure 4: Body Diode Characteristics

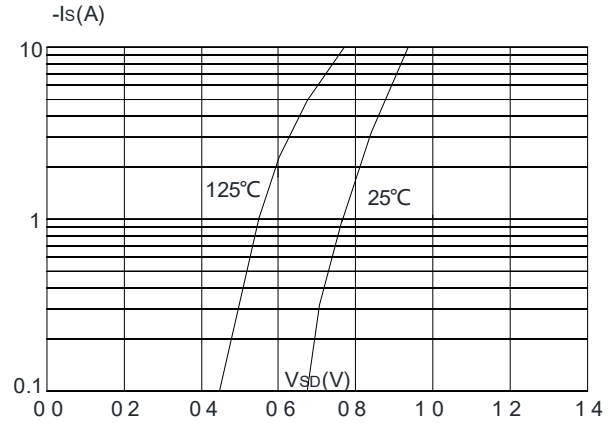


Figure 5: Gate Charge Characteristics

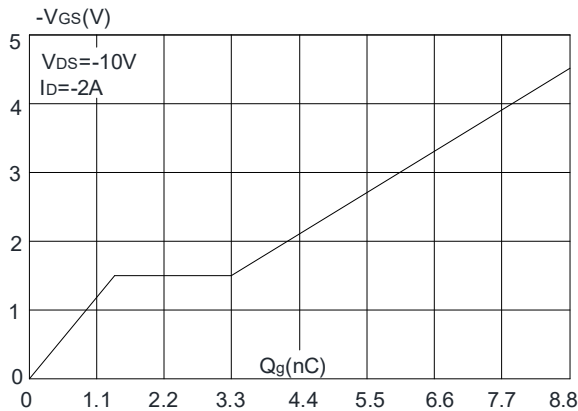
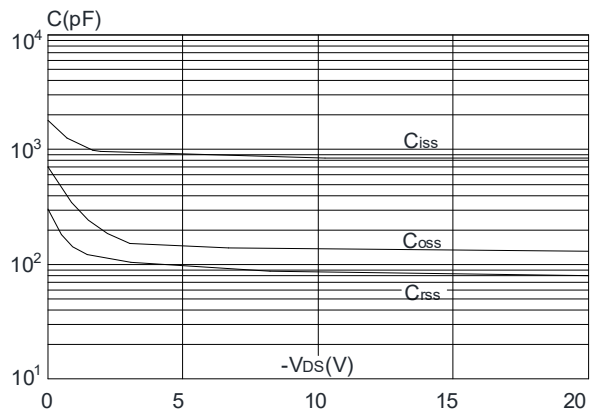


Figure 6: Capacitance Characteristics



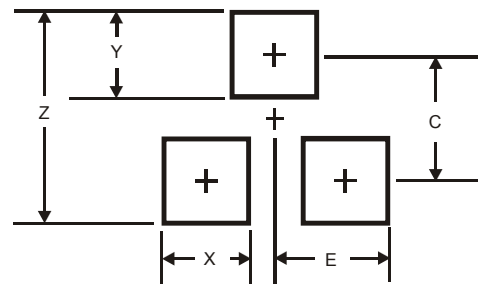
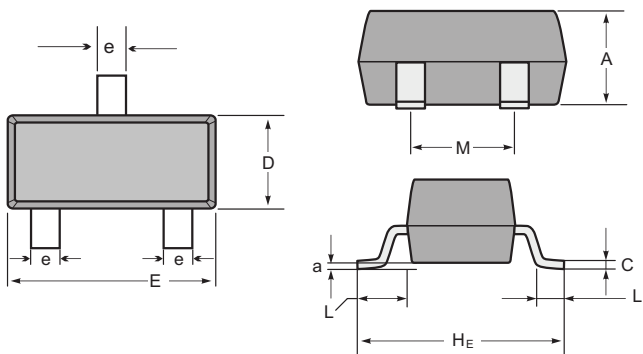
Soldering parameters

| Reflow Condition | | Pb-Free assembly (see as below) |
|---|-----------------------------------|------------------------------------|
| Pre Heat | -Temperature Min ($T_{s(min)}$) | +150 °C |
| | -Temperature Max($T_{s(max)}$) | +200 °C |
| | -Time (Min to Max) (ts) | 60-180 secs. |
| Average ramp up rate (Liquid us Temp (T_L) to peak) | | 3 °C/sec. Max |
| $T_{s(max)}$ to T_L - Ramp-up Rate | | 3 °C/sec. Max |
| Reflow | -Temperature(T_L)(Liquid us) | +217 °C |
| | -Temperature(t_L) | 60-150 secs. |
| Peak Temp (T_P) | | +260(+0/-5) °C |
| Time within 5 °C of actual Peak Temp (t_p) | | 30 secs. Max |
| Ramp-down Rate | | 6 °C/sec. Max |
| Time 25 °C to Peak Temp (T_P) | | 8 min. Max |
| Do not exceed | | +260 °C |



Package Dimensions & Suggested Pad Layout

SOT23

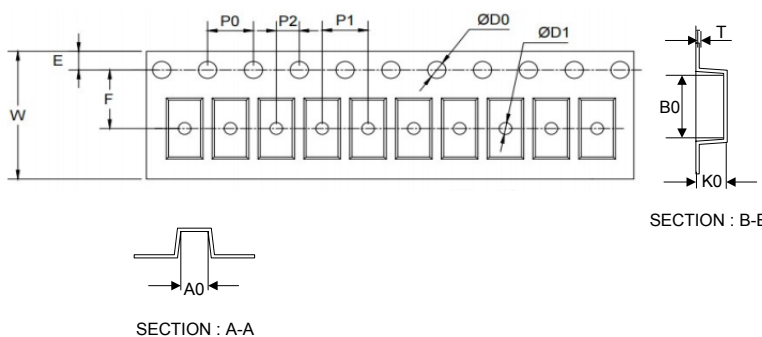
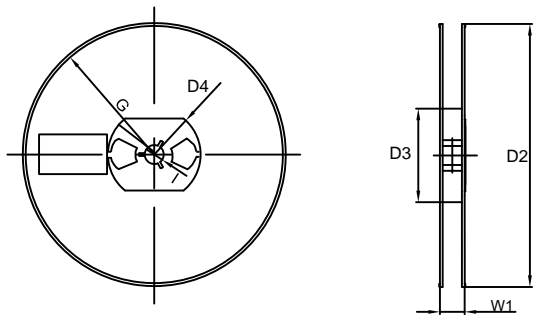


SOT-23 mechanical data

| UNIT | A | C | D | E | HE | e | M | L | L1 | a | |
|------|-----|-----|------|-----|-----|-----|-----|------|------------|------------|------|
| mm | max | 1.1 | 0.15 | 1.4 | 3.0 | 2.6 | 0.5 | 1.95 | 0.55 (ref) | 0.36 (ref) | 0.0 |
| | min | 0.9 | 0.08 | 1.2 | 2.8 | 2.2 | 0.3 | 1.7 | | | 0.15 |
| mil | max | 43 | 6 | 55 | 118 | 102 | 20 | 77 | 22 (ref) | 14 (ref) | 0.0 |
| | min | 35 | 3 | 47 | 110 | 87 | 12 | 67 | | | 6 |

| Dimensions | SOT23 |
|------------|-------|
| Z | 2.9 |
| X | 0.8 |
| Y | 0.9 |
| C | 2.0 |
| E | 1.35 |

Tape & reel specification

| Tape | Symbol | Dimension (mm) | |
|---|--|----------------|-----------|
|  | P0 | 4.00±0.10 | |
| | P1 | 4.00±0.10 | |
| | P2 | 2.00±0.10 | |
| | D0 | 1.55±0.10 | |
| | D1 | 1.05±0.10 | |
| | E | 1.55±0.10 | |
| | F | 3.60±0.10 | |
| | W | 8.00±0.10 | |
| | A0 | 3.80±0.20 | |
| | B0 | 3.25±0.20 | |
| | K0 | 1.45±0.10 | |
| | T | 0.25±0.05 | |
| | <p>7" Reel</p>  | D2 | 178.0±3.0 |
| | | D3 | 55Min. |
| | | D4 | R24.0±3.0 |
| G | | R82.0±3.0 | |
| I | | 13.0±2.0 | |
| W1 | | 11.0±3.0 | |
| Quantity: 3000PCS | | | |